

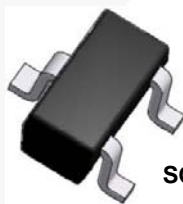


August 2015

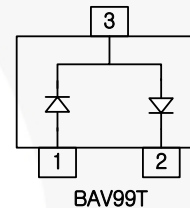
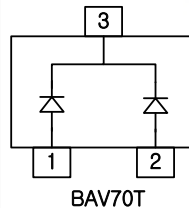
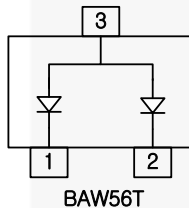
# BAW56T / BAV70T / BAV99T Fast Switching Diode

## Features

- Fast Switching Diodes with  $T_{rr} < 4.0$  nsec
- Surface Mount Device at 0.95 mm Maximum Height
- MSL 1 per J-STD-020
- Pb Free and RoHS Compliant
- Matte Sn Lead Finish
- Green Mold Compound



SOT-523



## Ordering Information

| Part Number | Top Mark | Package    | Packing Method |
|-------------|----------|------------|----------------|
| BAW56T      | JD       | SOT-523 3L | Tape and Reel  |
| BAV70T      | JJ       | SOT-523 3L | Tape and Reel  |
| BAV99T      | JE       | SOT-523 3L | Tape and Reel  |

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

| Symbol      | Parameter                          | Value        | Unit             |
|-------------|------------------------------------|--------------|------------------|
| $V_{RRM}$   | Maximum Repetitive Reverse Voltage | 85           | V                |
| $I_{F(AV)}$ | Average Rectified Forward Current  | Single Diode | 150              |
|             |                                    | Dual Diodes  | 75               |
| $T_J$       | Operating Junction Temperature     | 125          | $^\circ\text{C}$ |
| $T_{STG}$   | Storage Temperature Range          | -55 to +125  | $^\circ\text{C}$ |

BAW56T / BAV70T / BAV99T — Fast Switching Diode

**Thermal Characteristics<sup>(1)</sup>**

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted.

| Symbol          | Parameter   | Value | Unit                      |
|-----------------|---|-------|---------------------------|
| $P_D$           | Power Dissipation   | 150   | mW                        |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient                                       | 500   | $^\circ\text{C}/\text{W}$ |
| $\Psi_{JL}$     | Junction-to-Lead Thermal Characteristics,<br>Thermocouple Soldered to Cathode | 195   | $^\circ\text{C}/\text{W}$ |

**Note:**

1. Device mounted on FR-4 PCB minimum land pad

**Electrical Characteristics**

Values are at  $T_A = 25^\circ\text{C}$  unless otherwise noted. Parameters are tested per individual diode.

| Symbol   | Parameter                 | Conditions  | Min. | Max.  | Unit          |
|----------|---------------------------|---|------|-------|---------------|
| $BV_R$   | Reverse Breakdown Voltage | $I_R = 1 \mu\text{A}$   | 85   |       | V             |
| $I_R$    | Reverse Leakage Current   | $V_R = 75 \text{ V}$  |      | 2     | $\mu\text{A}$ |
|          |                           | $V_R = 25 \text{ V}$  |      | 0.03  |               |
| $V_F$    | Forward Voltage           | $I_F = 1 \text{ mA}$  |      | 0.715 | V             |
|          |                           | $I_F = 10 \text{ mA}$   |      | 0.855 |               |
|          |                           | $I_F = 50 \text{ mA}$   |      | 1.00  |               |
|          |                           | $I_F = 150 \text{ mA}$  |      | 1.25  |               |
| $C_D$    | Diode Capacitance         | $V_R = 0 \text{ V}$ , $f = 1 \text{ MHz}$                                     |      | 4     | pF            |
| $T_{rr}$ | Reverse Recovery Time     | $I_F = I_R = 10 \text{ mA}$ , $I_{RR} = 0.1 \times I_R$<br>$R_L = 100 \Omega$ |      | 4     | ns            |

### Typical Performance Characteristics

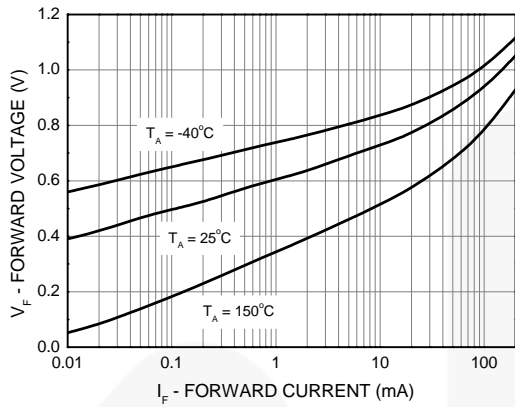


Figure 1. Forward Voltage vs. Forward Current

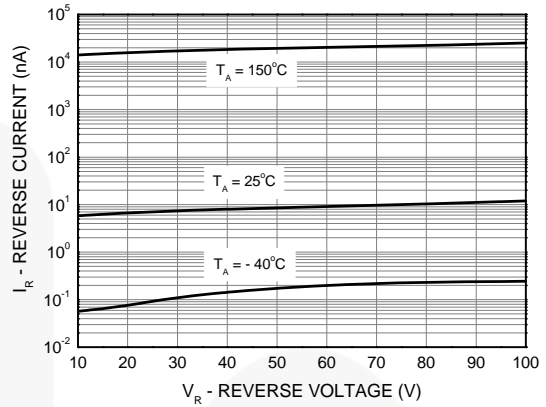


Figure 2. Reverse Current vs. Reverse Voltage

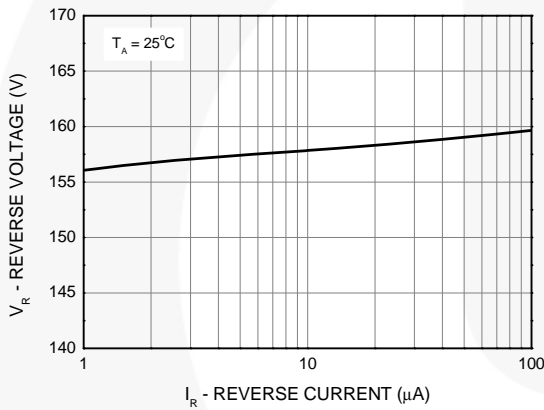


Figure 3. Reverse Voltage vs. Reverse Current

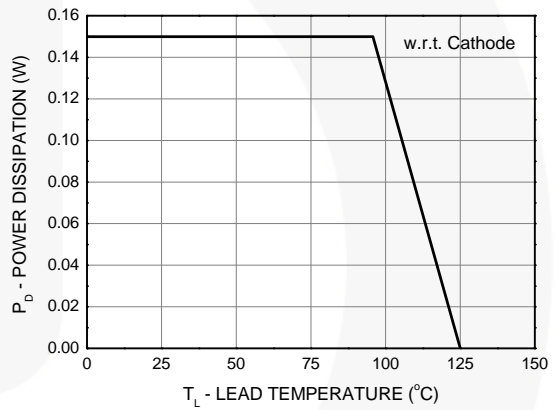


Figure 4. Power Derating Curve

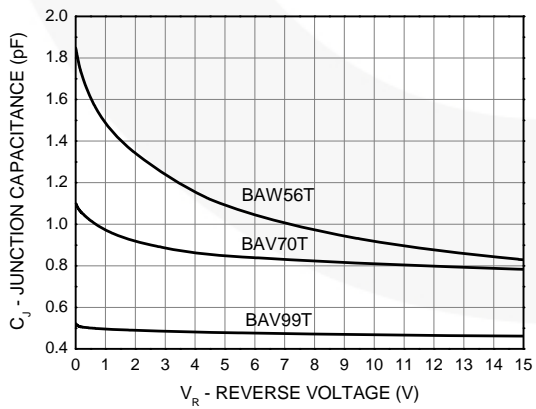
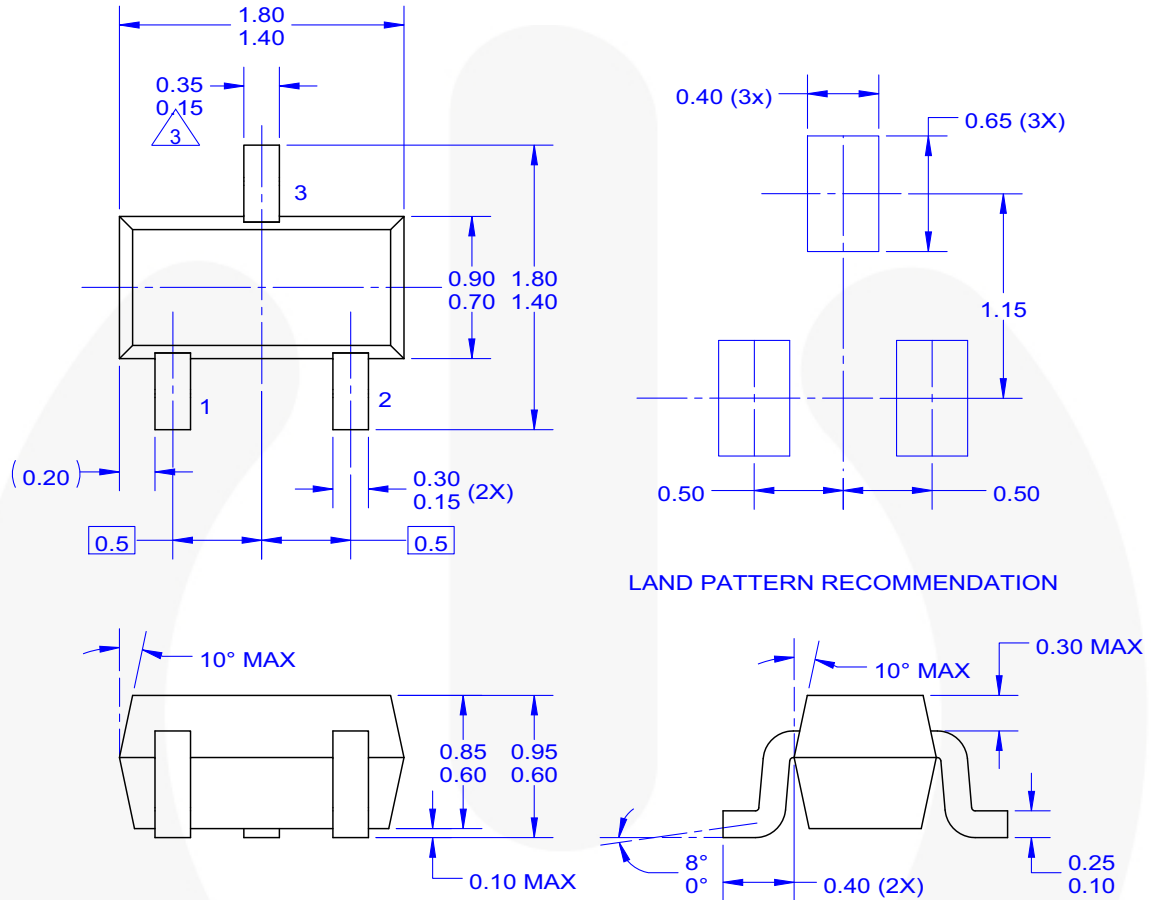


Figure 5. Total Capacitance vs. Reverse Voltage

Physical Dimensions



NOTES:






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- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DOES NOT COMPLY EIAJ SC75 STANDARD.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. LAND PATTERN RECOMMENDATION BASE FROM EIAJ STD.
- F. DRAWING FILE NAME: MKT-MAD03B REV1

Figure 6. 3-Lead, SOT523



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